

Aptek 6110-A/B Epoxy Encapsulant and/or Potting Compound

Category : Polymer , Thermoset , Epoxy , Epoxy Encapsulant, Unreinforced

Material Notes:

Optoelectronic grade encapsulant/potting compound – will not attack/cloud polysulphone casings. More flexible, lower Tg version of APTEK 6106-A/B, for good temperature cycling in ceramic devices. Part A is pale yellow to pale blue. Part B is water clear. Information provided by Aptek Laboratories, Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Aptek-6110-AB-Epoxy-Encapsulant-andor-Potting-Compound.php

Physical Properties	Metric	English	Comments
Density	0.940 g/cc	0.0340 lb/in ³	B Component; ASTM D1475
	1.15 g/cc	0.0415 lb/in ³	A Component; ASTM D1475
Viscosity	65 cP	65 cP	B Component; Spindle #2; speed 100 rpm; ASTM D1824
	3400 cP	3400 cP	A Component; Spindle #3; speed 10 rpm; ASTM D1824

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	85	85	Cured property; ASTM D2240

Thermal Properties	Metric	English	Comments
Flash Point	>= 100 °C	>= 212 °F	B Component; ASTM D92
	>= 200 °C	>= 392 °F	A Component; ASTM D92

Electrical Properties	Metric	English	Comments
Volume Resistivity	>= 1.00e+15 ohm-cm	>= 1.00e+15 ohm-cm	Cured property; ASTM D257

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